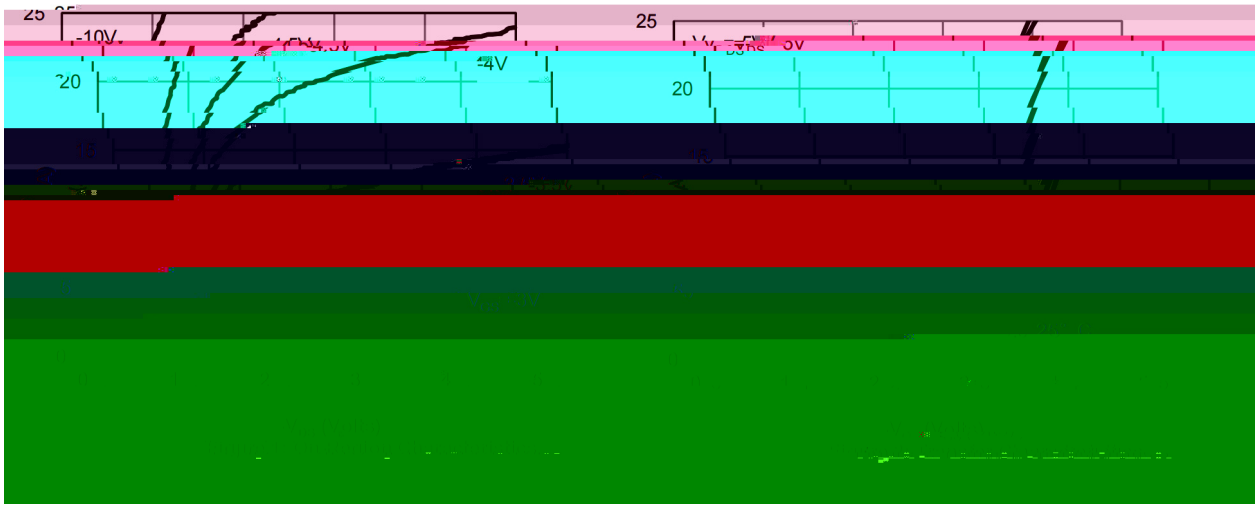
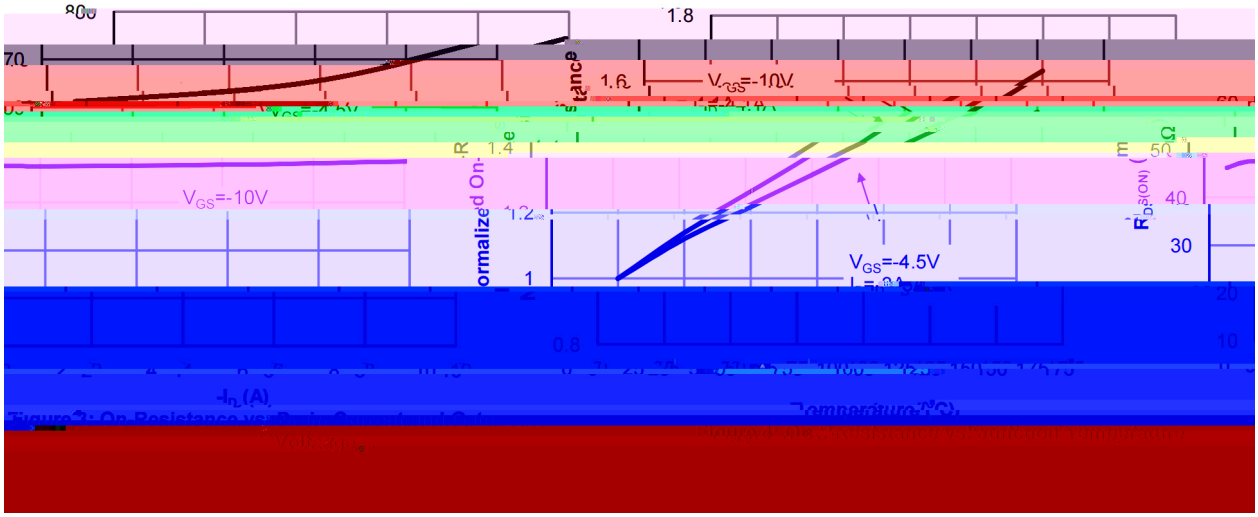
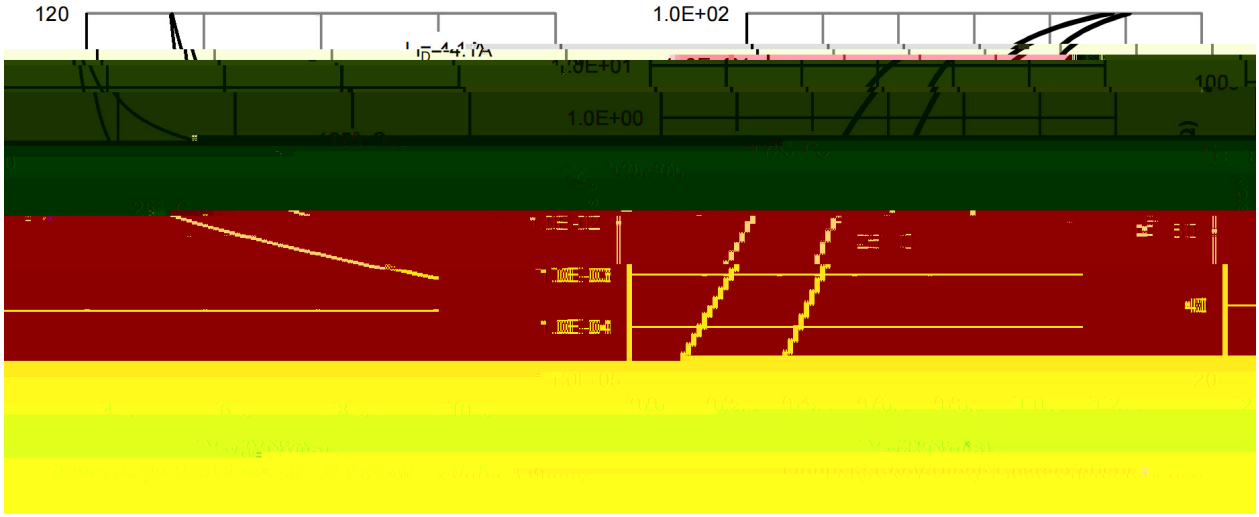
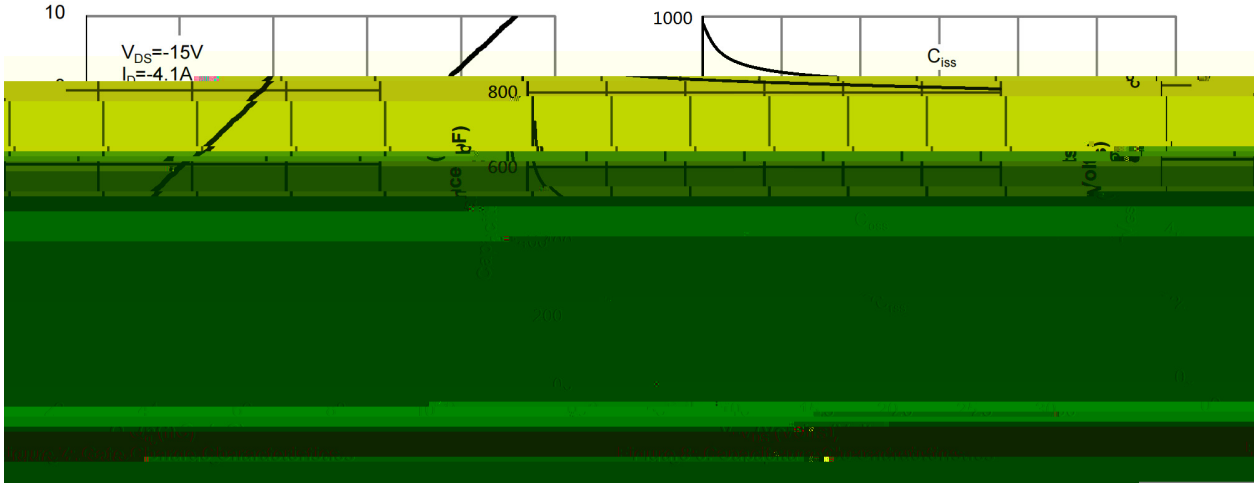
/ Electrical Characteristic Curve

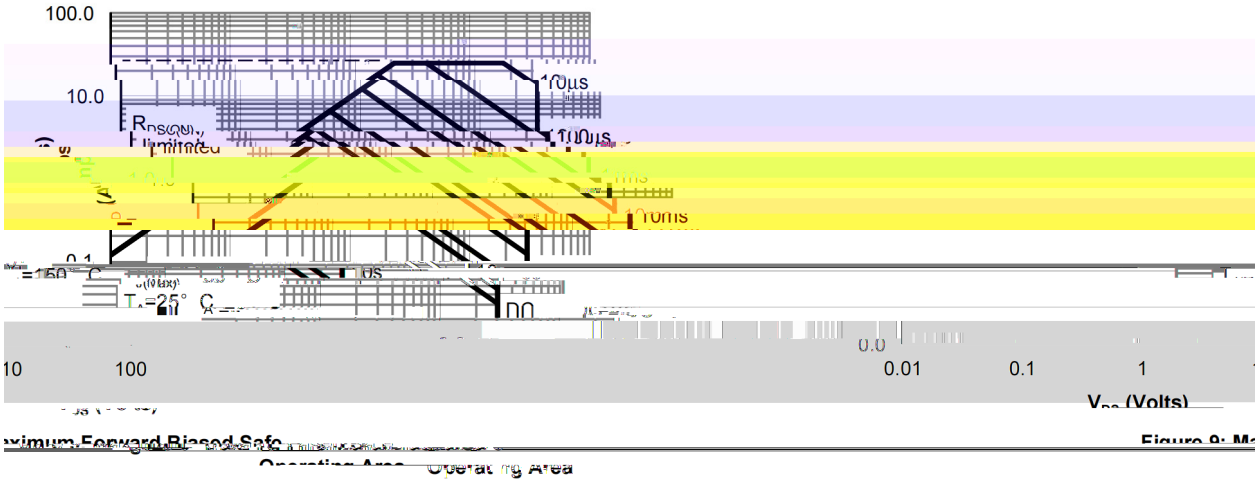


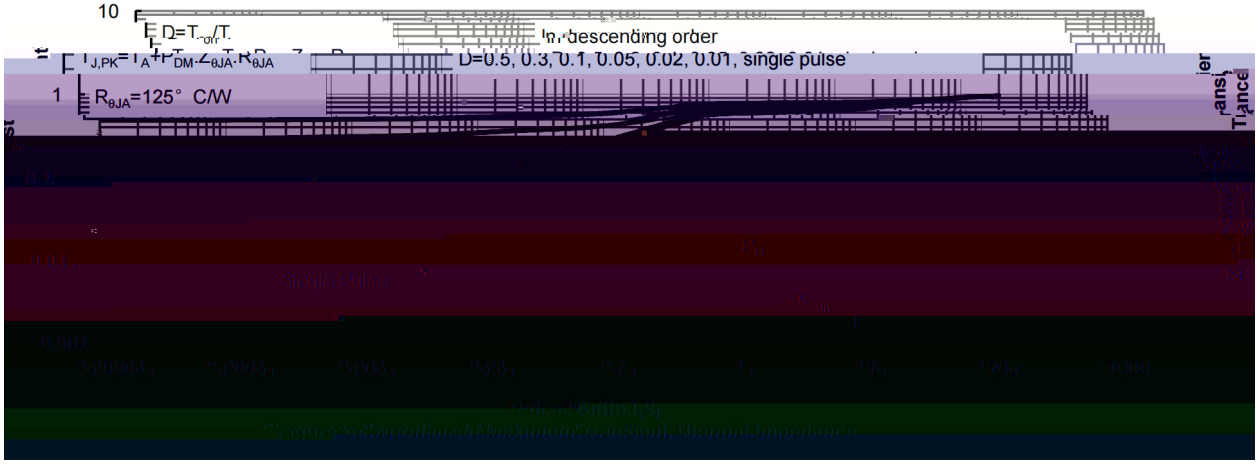




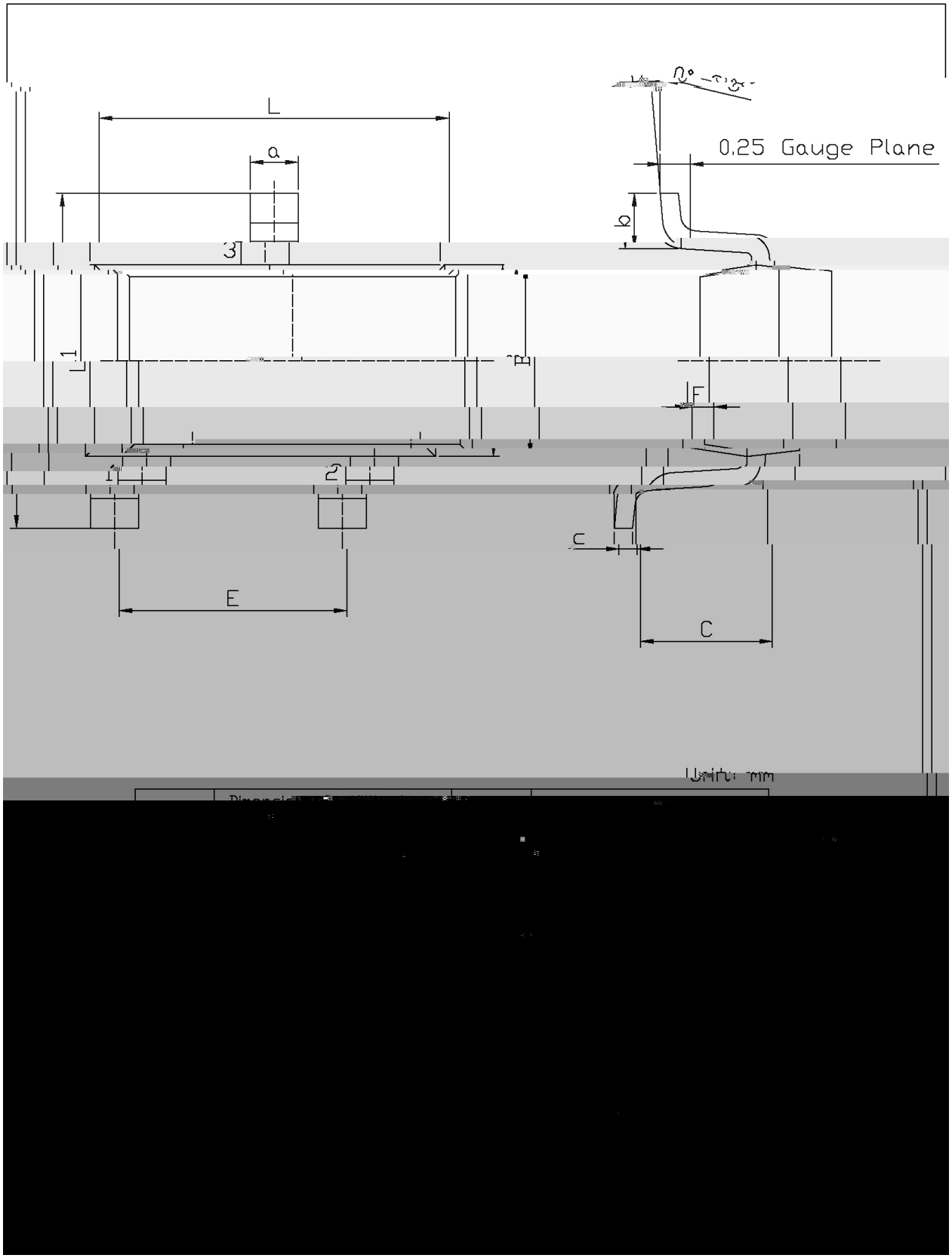
/ Electrical Characteristic Curve







/ Package Dimensions



( ) / Temperature Profile for IR Reflow Soldering(Pb-Free)

		Note:
1	150 180 60 90sec;	1.Preheating:150~180 , Time:60~90sec.
2	245±5 5±0.5sec;	2.Peak Temp.:245±5 , Duration:5±0.5sec.
3	2 10 /sec.	3. Cooling Speed: 2~10 /sec.

/ Resistance to Soldering Heat Test Conditions

260±5	10±1 sec.	Temp.:260±5	Time:10±1 sec

/ Packaging SPEC.

/ REEL